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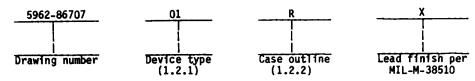
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DESC FORM 193

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1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part number. The complete part number shall be as shown in the following example:



1.2.1 Device types. The device types shall identify the circuit function as follows:

Device type	Generic number	Circuit function
01	2965	Octal dynamic memory driver with three-state outputs and inverting drivers
02	2966	Octal dynamic memory driver with three-state outputs and non-inverting drivers

1.2.2 <u>Case outlines</u>. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows:

Outline letter R D-8 (20-lead, 1/4" x 1 1/16"), dual-in-line package C-2 (20-terminal, .350" x .350"), square chip carrier package

1.3 Absolute maximum ratings.

1.4 Recommended operating conditions.

Must withstand the added P_D due to short circuit test (e.g., I_{OS}).

When a thermal resistance value for this case is included in MiL-M-38510, appendix C, that value shall supersede the value indicated herein.

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2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510

- Microcircuits, General Specification for

STANDARD

MILITARY

MIL-STD-883

- Test Methods and Procedures for Microelectronics

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

- 2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.
 - 3. REQUIREMENTS
- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- 3.2 Design, construction, and physical dimensions. The design, construction and physical dimensions shall be as specified in MIL-M-38510 and herein.
 - 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.
 - 3.2.2 Logic diagram. The logic diagram shall be as specified on figure 2.
 - 3.2.3 Truth table. The truth table shall be as specified on figure 3.
 - 3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
- 3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full recommended case operating temperature range.
- 3.4 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.
- 3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.

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Test	 Symbol	Symbol Conditions				Device	Group /		Limits		İ
		+55 4.5 (unles	°C < Tr -	<pre>< +125°C < 5.5 V ise speci</pre>	fied)	Туре	subgroup	ps Mi	n Max] 	
Output high voltage	VOH 1	V _{CC} = 4 V _{IN} = V I _{OH} = -	IH or VI	5.5 V <u>1</u> ,	', 	A11	1, 2,	3 V _C	Î5	V	
Output low voltage	V _{OL1}	V _{CC} = 4	.5 V,	I _{OL} = 1	0 mA	A11	1, 2,	3	0.5	V	_
	V _{OL2}	VIN = V	IH or	I _{OL} = 12	2 mA	All	1, 2,	3	0.8	V	
Input high voltage	I VIH	 <u>2</u> /				A11	1, 2,	3 2.0		 V	_
Input low voltage	V _{IL}	 <u>2</u> /	2/			A11	1, 2,	3	0.8	٧	_
Input clamp voltage	V _{IC}	V _{CC} = 4	.5 V, I _I	N = -18 i	nA	A11	1, 2,	3	-1.2	V	_
Input low current	IIL	V _{CC} = 5	.5 V,	DATA		A11	1, 2,	3	-200	μA	_
	 	V _{IN} = 0	.4 V	1G, 2G	 	A11	1, 2,	3	-400	μА	_
Input high current	I _{IH1}	V _{CC} = 5	.5 V	V _{IN} = 2	.7 ۷	A11	1, 2,	3	20	μА	_
	I _{IH2}			V _{IN} = 7	.o v	A11	1, 2,	3	0.1	mA	-
Off-state output current	IOZH	V _{CC} = 5	.5 V,	$V_0 = 2$.	7 V	A11	1, 2,	3	100	μА	_
	IOZL	G = VIH		v ₀ = 0.	١٧	A11	1, 2,	3	-200	μA	per
Output sink current	IOL	V _{CC} = 4	.5 V, V ₀	L = 2.0	, <u> </u>	A11	1, 2,	3 (50	Je	l mA	_
Output source current	IOH	V _{CC} = 4	.5 V, V ₀	H = 2.0	<i>'</i>	A11	1, 2,	3 -35	- 	i mA	_
Output short-circuit current	105	V _{CC} = 5	.5 V, V ₀	= 0 V <u>3</u>	/ i	A11	1, 2,	3 -60	-200 	i mA	
See footnotes at end of	table.										
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TABLE I. Electrical performance characteristics - Continued. Unit Limits Group A Symbol Conditions Device Test $-55^{\circ}\text{C} < \text{T}_{\text{C}} < +125^{\circ}\text{C}$ $4.5 \text{ V} < \text{V}_{\text{CC}} < 5.5 \text{ V}$ (unless otherwise specified) Min | Max Type subgroups 50 mΑ 1, 2, 3 V_{CC} = 5.5 V, Outputs 01 Supply current I_{CC1} Outputs open high 75 mΑ 1, 2, 3 02 125 mΑ 1, 2, 3 Outputs 01 I_{CC2} l l ow 130 mΑ 02 1, 2, 3 125 mΑ 1, 2, 3 Outputs 01 I_{CC3} lhi-Z 150 mΑ 1, 2, 3 02 7, 8 See 4.3.1c A11 Functional tests $|V_{CC}| = 5.0 \text{ V}, C_L = 50 \text{ pF},$ $|T_C| = +25 \text{ C}$ 9 6.0 15 ns A11 Propagation delay t_{PLH1} time, from low to high output (see figure 4) 20 19, 10, 11 4.0 ns A11 $C_L = 50 pF$ tpLH2 30 $C_L = 500 \text{ pF}, T_C = +25^{\circ}C \frac{4}{}$ 18 ns A11 tpLH3 18 40 A11 ns $|C_{L} = 500 \text{ pF } \frac{4}{4}$ t_{PLH4} V_{CC} = 5.0 V, C_L = 50 pF, 15 A11 9 5.0 ns Propagation delay time, from high to low output (see figure 4) tPHL1 6.0 22 $|C_L = 50 pF$ 01 9, 10, 11 ns tPHL2 20 9, 10, 11 4.0 ns 02 30 ns ICL = 500 pF, Tc = +25°C 4/ A11 tpHL3 18 40 A11 ns ICL = 500 pF 4/ tpHL4 | V_{CC} = 5.0 V, C_L = 50 pF, A11 9 20 ns Output enable time tPLZ1 from low (see figure 5) 10, 11 24 A11 ns $|C_L = 50 pF$ tpLZ2

See footnotes at end of table.

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т/	ABLE I. <u>E</u>	lectrical performance character	istics -	Continued.			
Test	Symbo1	Conditions $\begin{array}{cccccccccccccccccccccccccccccccccccc$	 Device Type 	 Group A subgroups 	Lim Min	its Max 	 Unit
Output enable time from high (see figure 5)	t _{PHZ1}		A11	9 	 	 12 	l ns l
	t _{PHZ2}	 C _L = 50 pF 	 A11 	10, 11	! ! !	 16 	l ns
Output disable time from low (see figure 5)	t _{PZL1}	V _{CC} = 5.0 V, C _L = 50 pF, T _C = +25 °C	 A11 	9	 	20	l ns
	t _{PZL2}	C _L = 50 pF	All	10, 11	 	 28 	l l ns
Output disable time from high (see figure 5)	t _{PZH1}		 A11 	 9 		 20 	ns
	t _{PZH2}	 C _L = 50 pF 	 A11 	10, 11		28 	ns
Output to output skew 5/	tskew	Y _{CC} = 5.0 V C _L = 50 pF, T _C = +25°C	I All	l I		+3.0	ns ·
Output voltage undershoot 5/	YONP	 C _L = 50 pF	 A11 	 	0 (-0.5	V

 $[\]underline{1}/$ V_{OH} is tested at both V_{CC} = 4.5 V and at V_{CC} = 5.5 V.

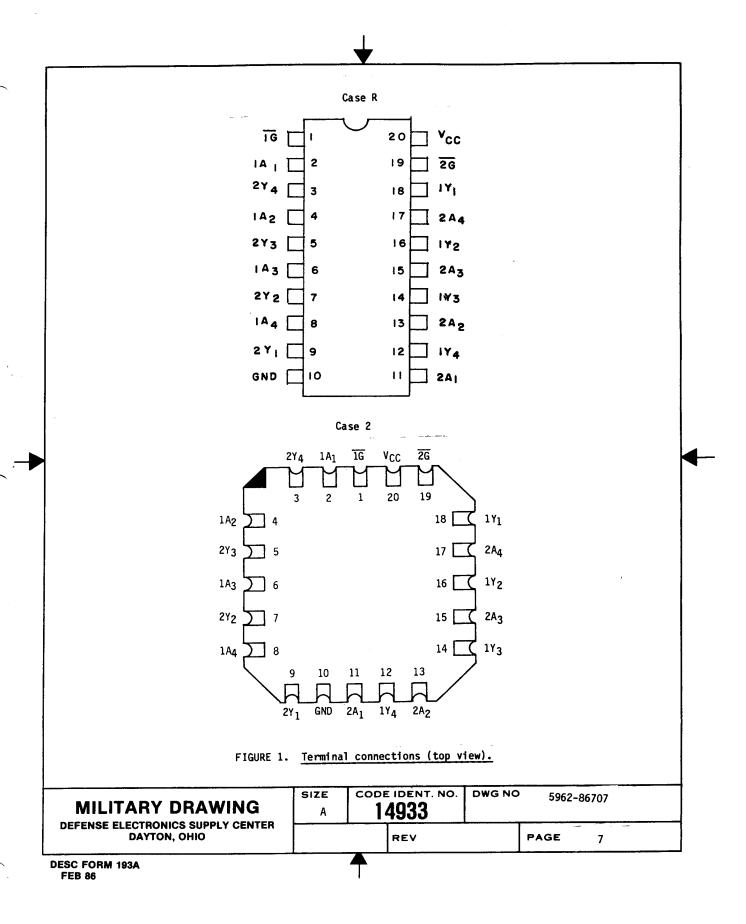
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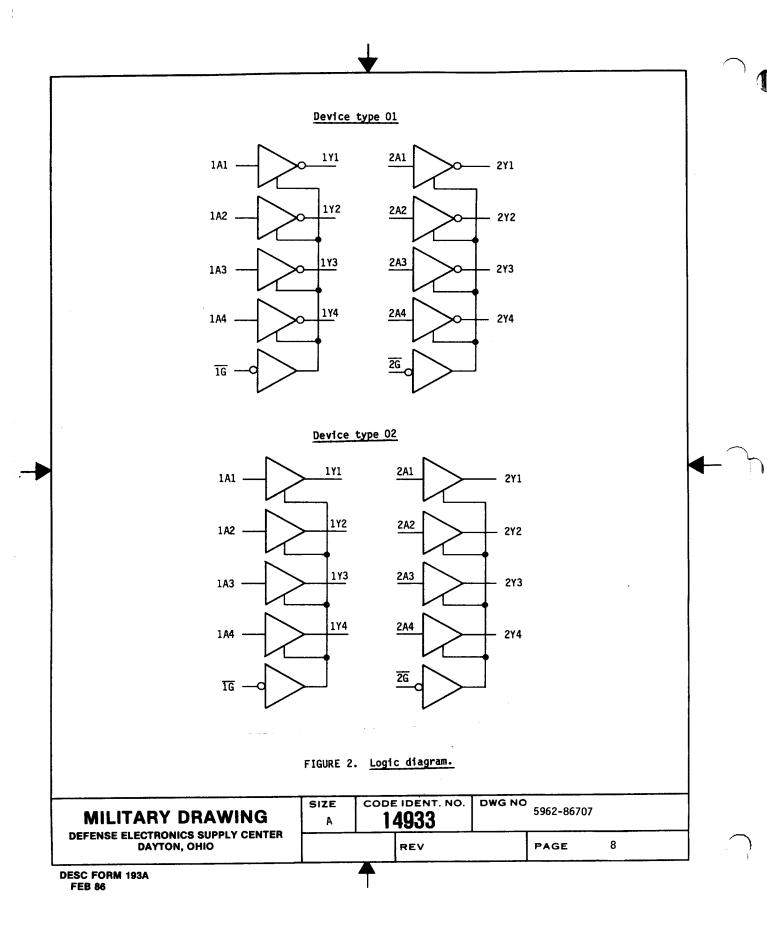
 $[\]underline{2}/$ Input thresholds are tested during DC tests and may be done in combination with testing of other DC parameters.

³/ Not more than one output should be shorted at a time. Duration of short-circuit should not exceed one second.

 $[\]underline{4}/$ 500 pF loads are not tested, but are correlated to 50 pF loads.

^{5/} Parameter guaranteed, but not tested.





Device type 01

T	Input	:s	Output	
T	G	Α	! ! Y !	1
	H L L	X H L	T Z L L H	

Device type 02

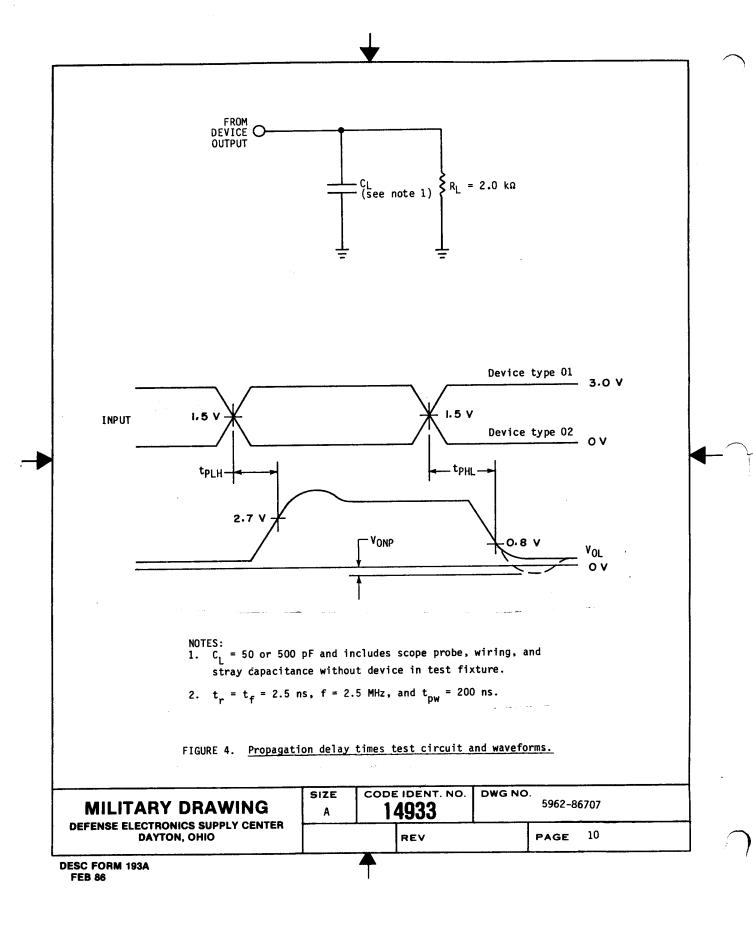
l I	nput	s	Output	
	G	A	 Y 	
İ	H L L	X L H	 Z L H	

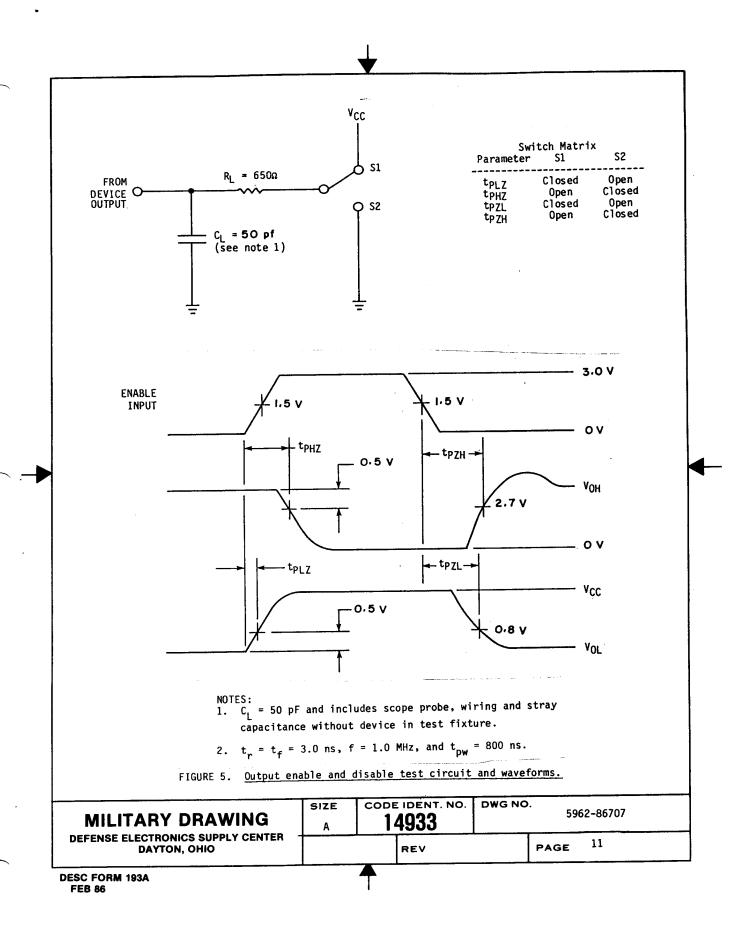
FIGURE 3. Truth table.

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- 3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.7 <u>Notification of change</u>. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.8 <u>Verification and review.</u> DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test (method 1015 of MIL-STD-883).
 - (1) Test condition A, B, C or D using the circuit submitted with the certificate of compliance (see 3.1 herein).
 - (2) $T_A = +125$ °C, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 4, 5, and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - c. Subgroups 7 and 8 tests sufficient to verify the function table.
 - 4.3.2 Groups C and D inspections.
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test (method 1005 of MIL-STD-883) conditions:
 - (1) Test condition A, B, C or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	***
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 8, 9, 10**, 11**
Group A test requirements (method 5005)	1, 2, 3, 7, 8, 9, 10**, 11**
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3
Additional electrical subgroups for group C periodic inspections	

* PDA applies to subgroup 1.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL+M-38510.

6. NOTES

- 6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

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^{**} Subgroups 10 and 11, if not tested, shall be guaranteed to the limits specified in table I.

6.4 Approved source of supply. An approved source of supply is listed herein. Additional sources will be added as they become available. The vendor listed herein has agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

 Military drawing part number	Vendor CAGE number	Vendor similar part number <u>1</u> /
5962-8670701RX	34335	AM2965/BRA
5962-86707012X	34335	AM2965/B2C
5962-8670702RX	34335	AM2966/BRA
5962-86707022X	34335	AM2966/B2C

 $\frac{1}{\text{Lems}}$ acquired to this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

34335

Vendor name and address

Advanced Micro Devices, Incorporated 901 Thompson Place Sunnyvale, CA 94088

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